

MOSFET – Power, Single, N-Channel, μ Cool, UDFN6, 1.6x1.6x0.55 mm

30 V, 18 m Ω , 6.9 A

NTLUS030N03C

Features

- UDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile UDFN 1.6 x 1.6 x 0.55 mm for Board Space Saving
- Ultra Low $R_{DS(on)}$
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Power Load Switch
- Wireless Charging
- DC-DC Converters
- Motor Drive

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	30	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $R_{\theta JA}$ (Note 1, 3)	Steady State	$T_A = 25^\circ\text{C}$	I_D 6.9 A
		$T_A = 85^\circ\text{C}$	
		$T_A = 25^\circ\text{C}$	
Power Dissipation $R_{\theta JA}$ (Note 1, 3)	P_D	1.49	W
Continuous Drain Current $R_{\theta JA}$ (Note 2, 3)	Steady State	$T_A = 25^\circ\text{C}$	I_D 4.5 A
		$T_A = 85^\circ\text{C}$	
		$T_A = 25^\circ\text{C}$	
Power Dissipation $R_{\theta JA}$ (Note 2, 3)	P_D	0.64	W
Pulsed Drain Current	$t_p = 10 \mu\text{s}$	I_{DM} 20	A
Operating Junction and Storage Temperature	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

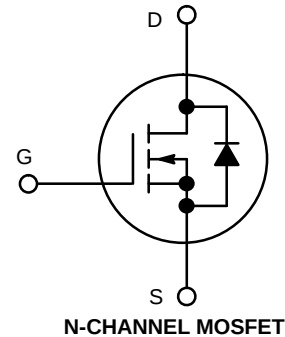
THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1, 3)	$R_{\theta JA}$	83.7	$^\circ\text{C/W}$
Junction-to-Ambient – Steady State min Pad (Note 2, 3)	$R_{\theta JA}$	196.6	

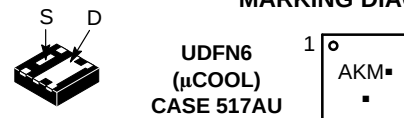
- Surface-mounted on FR4 board using 1 in² pad size, 2 oz Cu pad.
- Surface-mounted on FR4 board using the min pad size, 2 oz Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- This device does not have ESD protection diode.

MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX
30 V	18 m Ω @ 10 V	6.9 A
	26 m Ω @ 4.5 V	



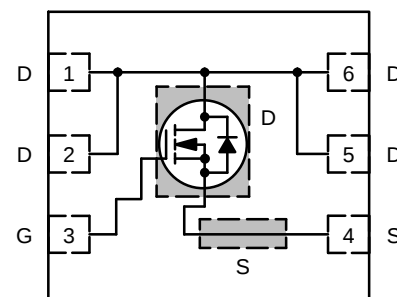
MARKING DIAGRAM



AK = Specific Device Code
M = Date Code
■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NTLUS030N03C

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 250\text{ }\mu\text{A}$, ref to $25\text{ }^{\circ}\text{C}$		14.2		mV/ $^{\circ}\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25\text{ }^{\circ}\text{C}$		1.0	μA
			$T_J = 125\text{ }^{\circ}\text{C}$		10	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$			100	nA

ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	1.2		2.2	V
Negative Threshold Temp. Coefficient	$V_{GS(TH)}/T_J$	$I_D = 250\text{ }\mu\text{A}$, ref to $25\text{ }^{\circ}\text{C}$		-4.1		mV/ $^{\circ}\text{C}$
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}$		14	18	m Ω
		$V_{GS} = 4.5\text{ V}, I_D = 5.0\text{ A}$		20	26	
Forward Transconductance	g_{FS}	$V_{DS} = 1.5\text{ V}, I_D = 5.0\text{ A}$		16		S

CHARGES & CAPACITANCES

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 15\text{ V}$		400		μF
Output Capacitance	C_{OSS}			215		
Reverse Transfer Capacitance	C_{RSS}			21		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 5.0\text{ A}$		3.7		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.6		
Gate-to-Source Charge	Q_{GS}			1.3		
Gate-to-Drain Charge	Q_{GD}			1.2		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}; I_D = 5.0\text{ A}$		8		nC

SWITCHING CHARACTERISTICS, $V_{GS} = 4.5\text{ V}$ (Note 6)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DD} = 15\text{ V}, I_D = 5.0\text{ A}, R_G = 6\text{ }\Omega$		9		ns
Rise Time	t_r			15		
Turn-Off Delay Time	$t_{d(OFF)}$			11		
Fall Time	t_f			2.5		

SWITCHING CHARACTERISTICS, $V_{GS} = 10\text{ V}$ (Note 6)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DD} = 15\text{ V}, I_D = 5.0\text{ A}, R_G = 6\text{ }\Omega$		6		ns
Rise Time	t_r			13		
Turn-Off Delay Time	$t_{d(OFF)}$			14		
Fall Time	t_f			2		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = 5.0\text{ A}$	$T_J = 25\text{ }^{\circ}\text{C}$		0.8	1.0	V
			$T_J = 125\text{ }^{\circ}\text{C}$		0.7		
Reverse Recovery Time	t_{RR}	$V_{GS} = 0\text{ V}, di/dt = 100\text{ A}/\mu\text{s}, I_S = 5.0\text{ A}$		20			ns
Charge Time	t_a			11			
Discharge Time	t_b			10			
Reverse Recovery Charge	Q_{RR}			8			nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

6. Switching characteristics are independent of operating junction temperatures.



TYPICAL CHARACTERISTICS

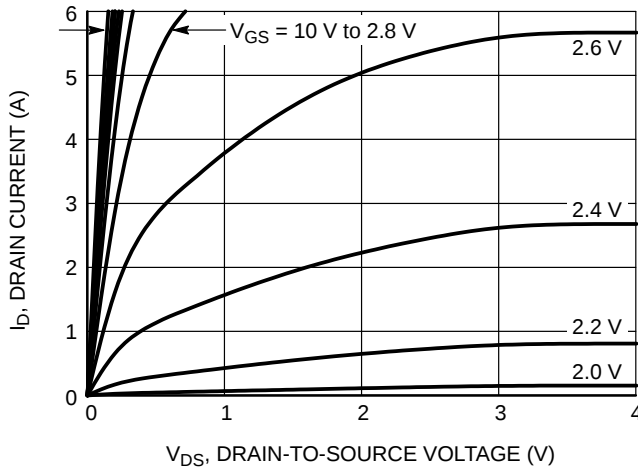


Figure 1. On-Region Characteristics

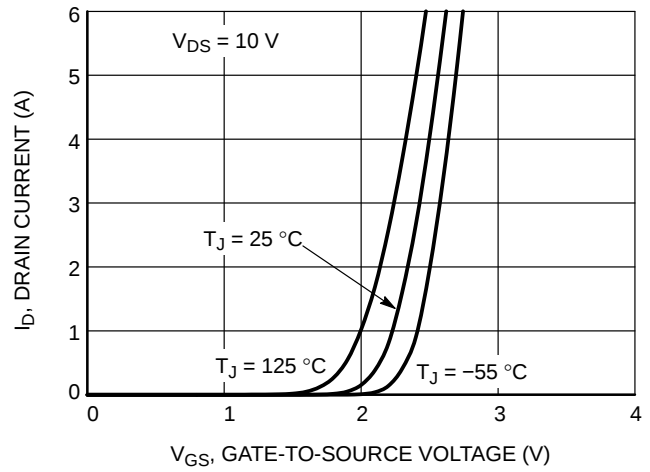


Figure 2. Transfer Characteristics

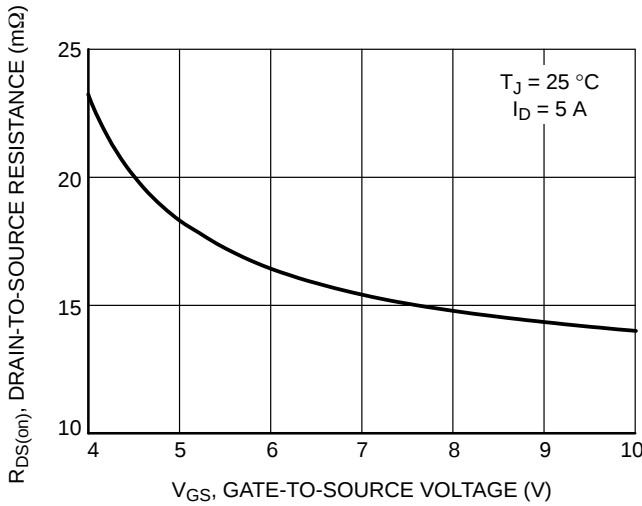


Figure 3. On-Resistance vs. Gate-to-Source Voltage

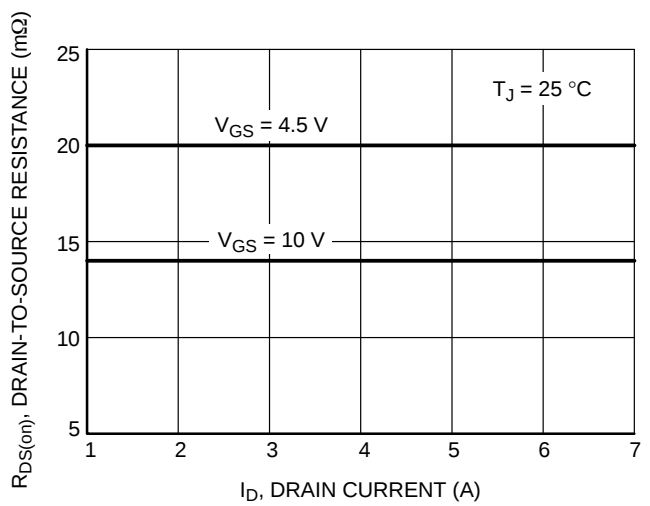


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

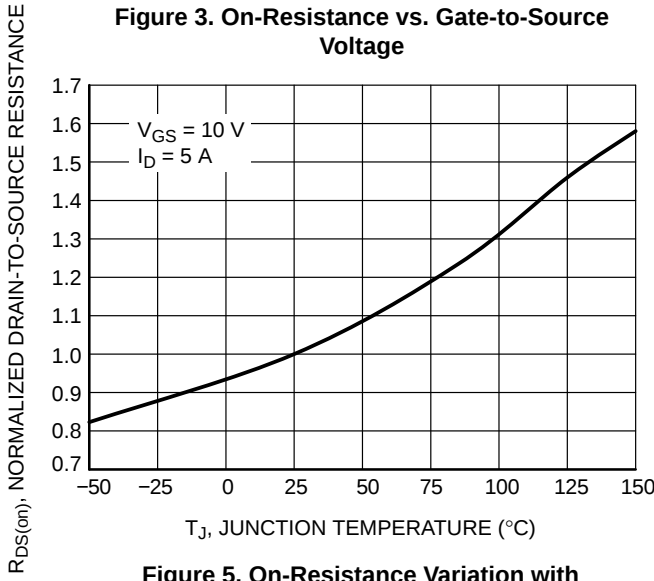


Figure 5. On-Resistance Variation with Temperature

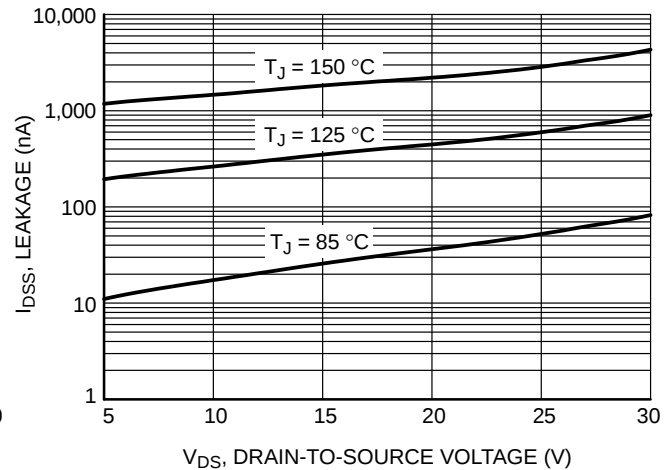


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

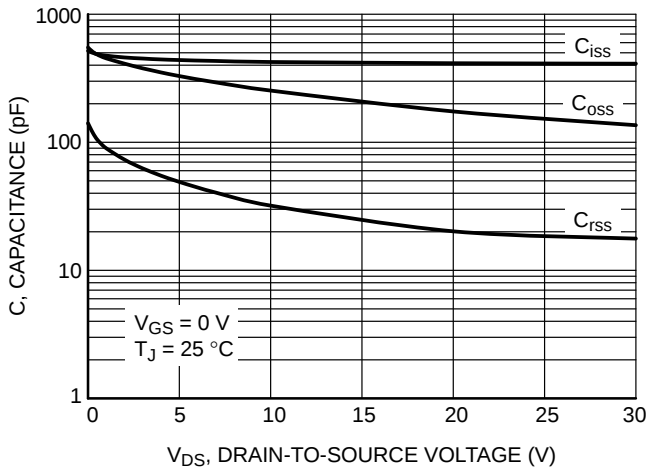


Figure 7. Capacitance Variation

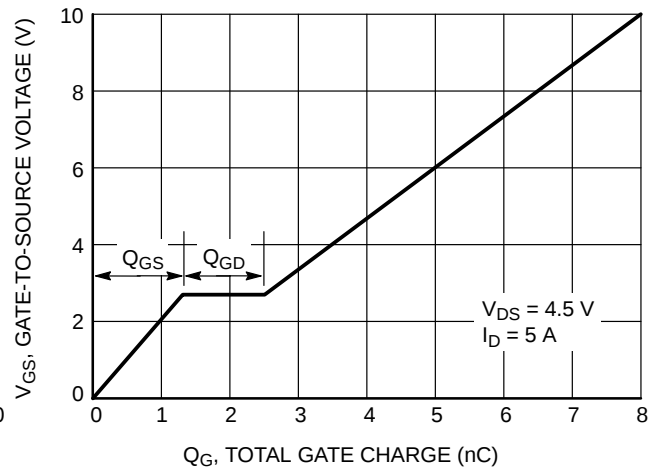


Figure 8. Gate-to-Source vs. Total Charge

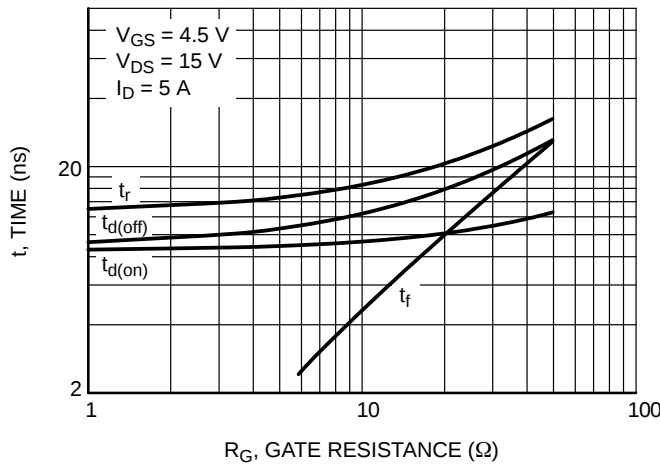


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

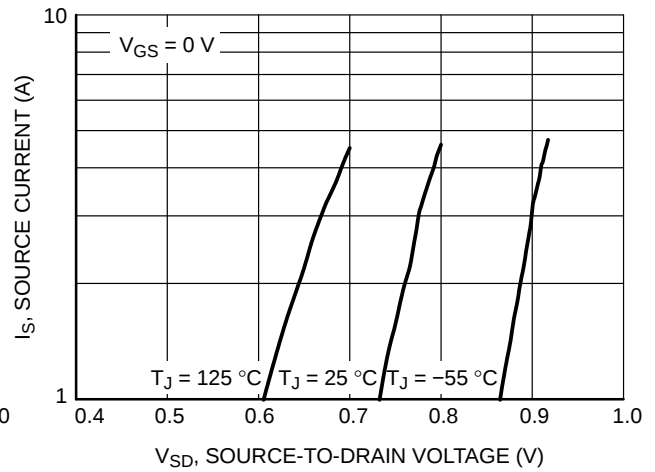


Figure 10. Diode Forward Voltage vs. Current

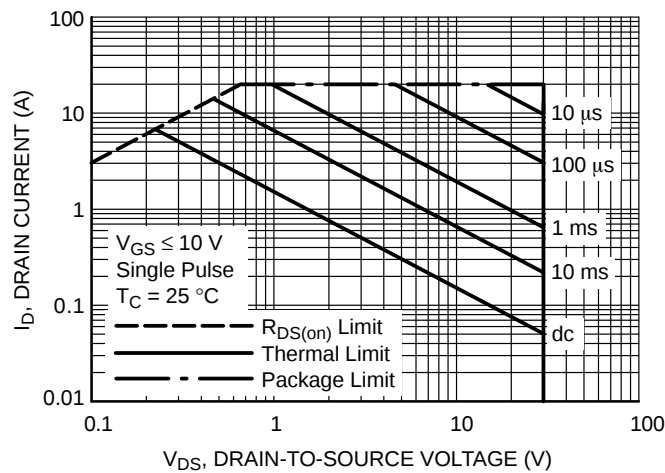


Figure 11. Maximum Rated Forward Biased Safe Operating Area

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TYPICAL CHARACTERISTICS

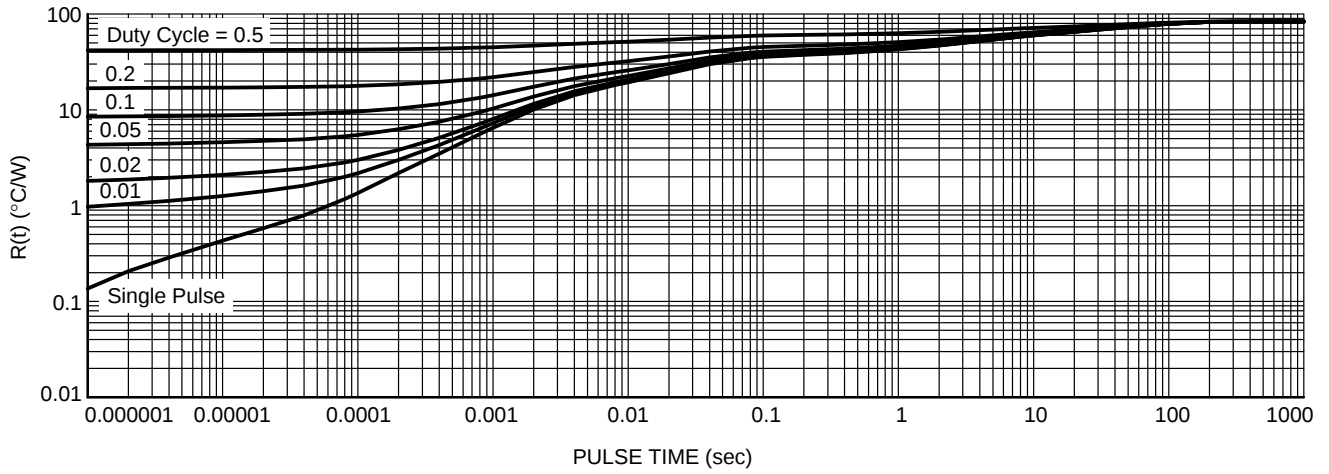


Figure 12. Thermal Response

DEVICE ORDERING INFORMATION

Device	Package	Shipping [†]
NTLUS030N03CTAG	UDFN6 (Pb-Free)	3000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

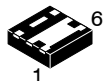


REVISION HISTORY

Revision	Description of Changes	Date
3	Rebranded the document to onsemi format.	1/27/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

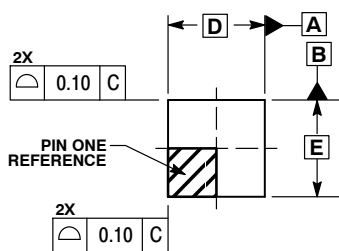




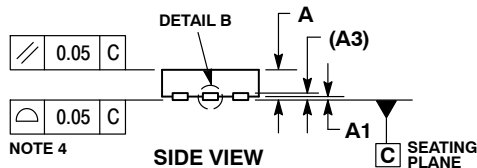
SCALE 4:1

UDFN6 1.6x1.6, 0.5P
CASE 517AU
ISSUE O

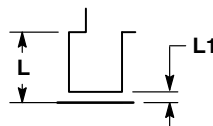
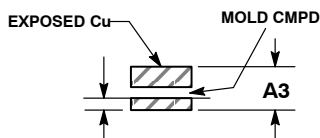
DATE 16 OCT 2008



TOP VIEW



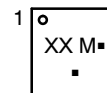
SIDE VIEW


DETAIL A
OPTIONAL
CONSTRUCTION

DETAIL B
OPTIONAL
CONSTRUCTION

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.20	0.30
D	1.60	BSC
E	1.60	BSC
e	0.50	BSC
D1	0.62	0.72
D2	0.15	0.25
E2	0.57	0.67
F	0.55	BSC
G	0.25	BSC
L	0.20	0.30
L1	---	0.15

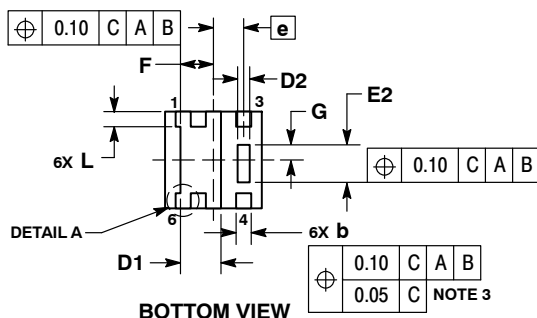
GENERIC
MARKING DIAGRAM*


XX = Specific Device Code

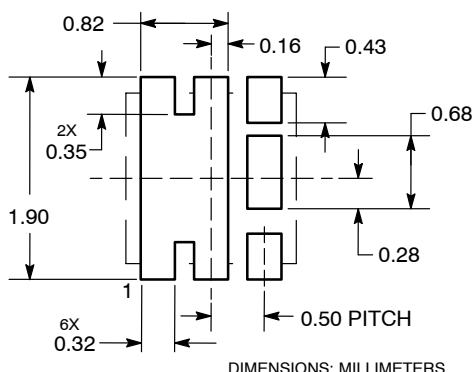
M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either loca-

tion)
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.


BOTTOM VIEW

SOLDERMASK DEFINED
MOUNTING FOOTPRINT*


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON35147E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	UDFN6 1.6x1.6, 0.5P	PAGE 1 OF 1

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